MSAP

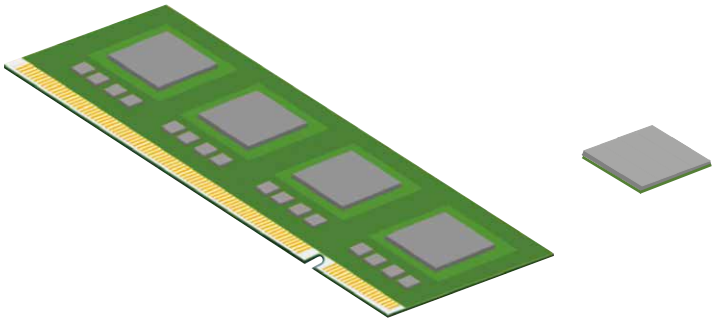
Modified Semi-Additive Process

特長 Features

- 高精細パターン形成
  High definition pattern formation
- パターン幅ばらつき低減
  Pattern width variation reduction

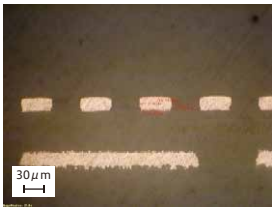
用途 Application

- メモリ、RFパターン
  Memory, Radio-Frequency pattern
- SiP
  Systen in package

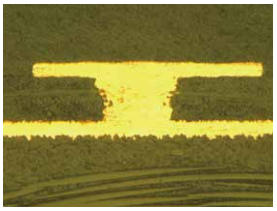


高精細パターン形成 High definition pattern formation

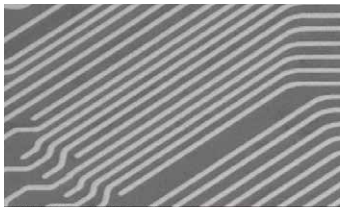
L/S=30/30
(Cross section)



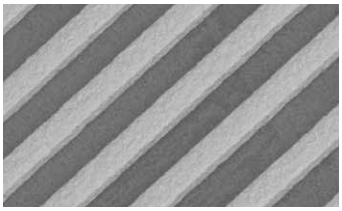
LVH(φ100)
(Cross section)



L/S=25/25

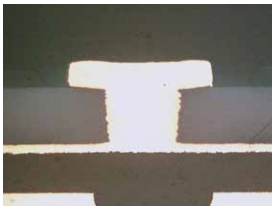


LVH(φ50)

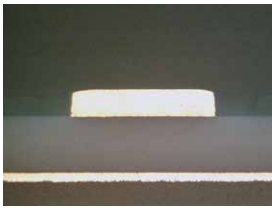


パターン幅ばらつき低減 Pattern width variation reduction

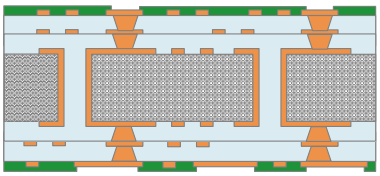
マイクロビア
Micro Via



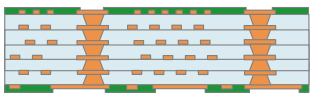
パターン形成(MSAP法)
Pattern(MSAP)



薄板対応 Compatible with thinner PCB thickness



従来
コア：60～100μm
PP　：40～60μm
Cu　：約15～20μm
(図の例では 約415μm)



コアレス
コア：なし
PP　：15～20μm
Cu　：約5～8μm
(図の例では 約180μm)

コアレス工法との組み合わせにより薄板対応可
Compatible with thinner PCB thickness by Coreless process

MEIKO